## **ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

SOLVENT FREE PHOTORESIST STRIP AND RESIDUE REMOVAL PROCESSING FOR POST ETCHING OF LOW-K FILMS

Application Number:

10/761122

Confirmation Number:

8790

First Named Applicant:

HUONG NGUYEN

Attorney Docket Number: AMAT5735C1

Search string:

('6214728 or 6130166 or 6124213 or 6074569 or 6062237 or 6046115 or 6043004 or 6037255 or 6030901 or 6024045 or 5811358 or 5681780 or 5660682 or 4357203 or 4028155 ).pn.

## **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

	ini	t	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
1			1	6214728	2001-04-10	CHAN, ET AL.	•		_
Ĭ	Ť	٦	2	6130166	2001-10-10	YEH	-		
Ĭ	Ť	٦	3	6124213	2000-09-26	USAMI, ET AL.			
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ľ	7	٦	5	6062237	2000-05-16	BROWN, ET AL.	] —		_
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K. Duda

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